



ALLNYX

www.allnyx.com

all about **Electronics**

Design > Development > Manufacturing



➤ Our Vision

to become a global leader in electronics manufacturing, design and engineering by catering diverse customer requirements and to create world class integrated facility giving one stop shop experience to customers



➤ Our Mission

to help customers through continuous improvements in quality systems & manufacturing processes to deliver quality products, solutions and services to help them to achieve their goals



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About Us



- Lakshya Group of Company
- Founded in 2015 at Dabhasa, Vadodara (Guj) India
- EMS Revenue Segment : 50% Job-work + 50% Turnkey
- Team size : 40
- No. of SMT Line : 01 (adding 02nd Line by June 27')
- No. of THT Line : 02



Achievements

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4000+
EMS/CEM
Projects

250+
Satisfied
Clients

1 to 7
Days
Quote

3 to 7
Days
Prototype

➤ Production **CAPACITY** * per shift

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2K⁺
Boards*
per day

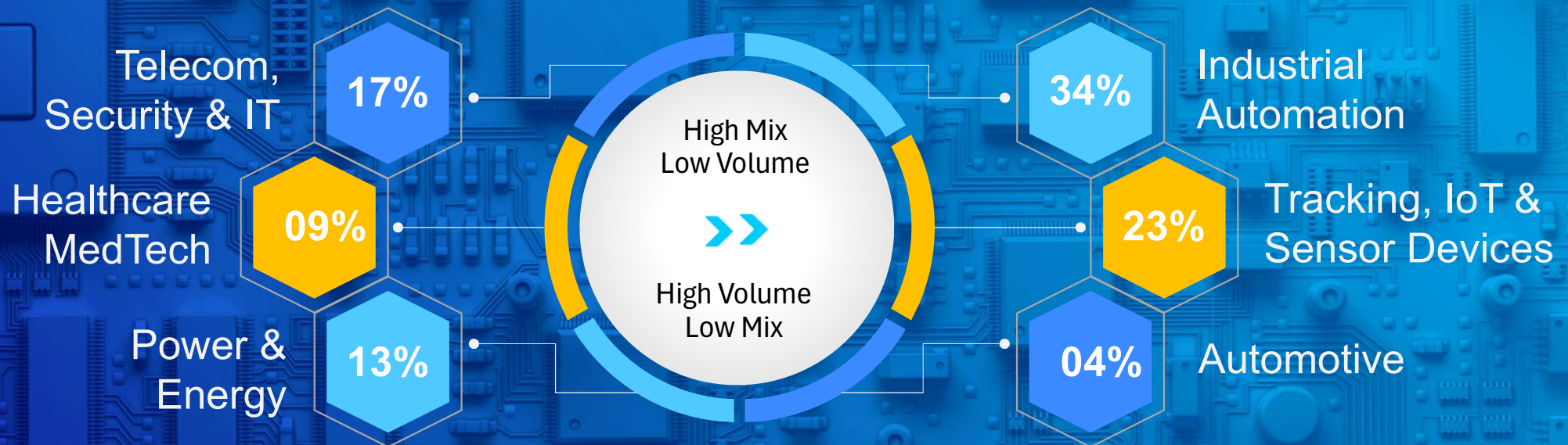


60K⁺
Boards*
per month



7L⁺
Boards*
per year

➤ INDUSTRY We Serve



SERVICES We Offer

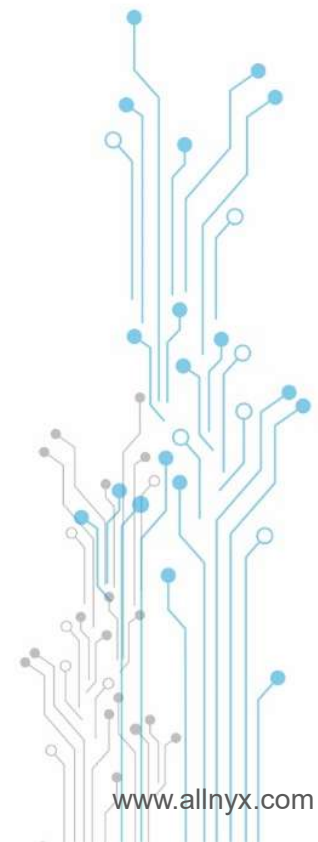


- Design & Engineering**
- Rapid Prototype & Pilot Projects
- OEM/ODM and Box-Build Solutions
- Value Engineering
- EMS / Contract Electronics Manufacturing : Job-work & Turnkey
- Supply Chain Management (Components)
- Electro-Mechanical**
- Assembling, Testing & Packing
- ** Outsourced

Our **EXPERTISE**

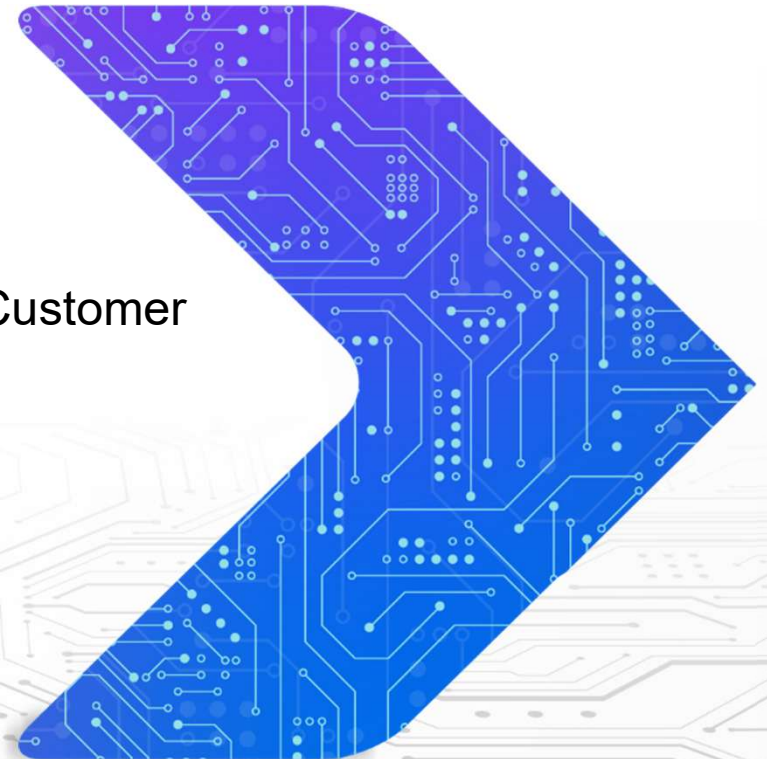


- Surface Mount (SMT) and Through Hole (THT) PCB Assembly
- PBGA (Pitch Ball Grid Array) & FBGA (Fine Ball Grid Array)
- Micro-BGA, CSP, Ultra-fine pitch QFP and QFN
- Fine Pitch (0201 and 01005) Components
- Manual - Conformal Coating & EPOXY Potting
- Components, Parts and Sub-Assemblies
- Board Level and System Level Testing
- Lead-Free, RoHS Compliant and Non-RoHS Manufacturing

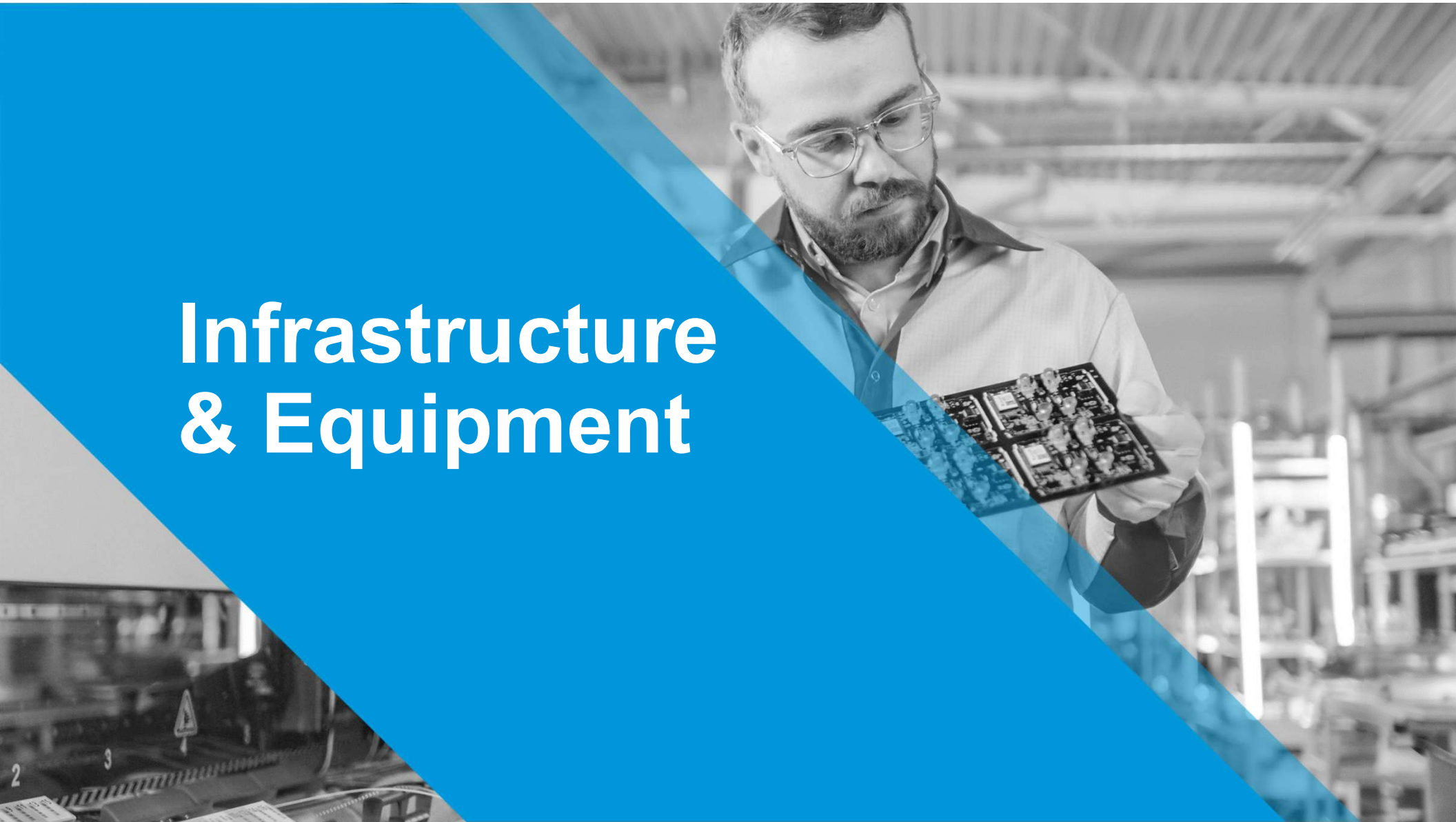


What Customer Can **EXPECT** from Us

- Business Ethics, Integrity & Transparency
- Extended EMS & Engineering Support
- Committed On Time Delivery
- Works in Eco systems → Supplier ➤ Allnyx ➤ Customer
- Integrated CEM / EMS Solutions at One Stop
- SPOC (Single Point of Contact)
- MNC Quality @ Indian Price
- Readiness to Invest in tools / equipment required to cater the need of projects



Infrastructure & Equipment



Infrastructure



Allnyx is an eminent Electronics Manufacturing Solution (EMS) providing company with SMT and THT lines.



Infrastructure - **PASTE Mixer**

- Adjustable Timer
- RoHS and Non-RoHS Paste
- Motor Speed: 1350 rpm (max)

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PASTE MIXER
OB-M628, CHINA

Infrastructure - **PRINTER**

- Process alignment capability
2 Cpk @ $\pm 20\mu\text{m}$ 6-Sigma
- Machine alignment capability
2 Cpk @ $\pm 12.5\mu\text{m}$ 6-Sigma
- Board Size: 510mm*510mm
- Cycle Time: 9Sec/Board
- Built-in **Stencil Cleaning** Functionality

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**STENCIL PRINTER
HORIZON 03IX, DEK
USA**

Infrastructure - SPI

- 3D Solder Paste Inspection Machine
- True 3D Volume Measurement
- High Accuracy and Repeatability
- Solder Paste Printing Optimization
- Histograms, X-bar & R-Chart, X-bar & S-chart, Cp & Cpk, and % of Gage R&R
- Real-time Data Visualization
- Warp Compensation Technology
- Real-time, Automatic Pad-Reference Teaching

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SOLDER PASTE INSPECTION

KY 8080

KOH YOUNG - KOREA

Infrastructure - Pick-n-Place

- 120 + 68 Feeders
- Automatic 20 Tray Changer
- Placement Accuracy: ± 30 micron Cpk ≥ 1.0
- Part Handling: 01005 to 120x90mm
- Intelligent Tape feeders & Stick Feeders
- Board Size: 510mm to 490mm
- Combined Rated Speed: 120,000 cph
- PanaCim Software for component traceability

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**PNP MACHINE
AM100 + D3A
PANASONIC
JAPAN**

Infrastructure - Reflow OVEN

- 9 Top and 9 Bottom Heating Zones
- 2 Cooling Zones
- Efficient Heat transfer
- Advanced 7 Thermocouple PCB profiling (KIC make)

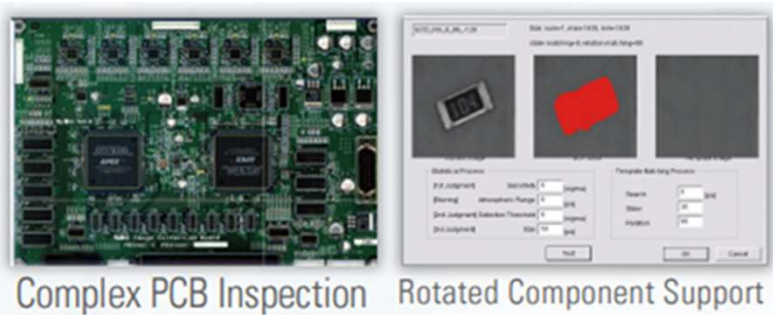
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**REFLOW OVEN
1809 MK7, HELLER
USA**

Infrastructure - AOI

- High-Speed, High-Precision 2D Visual Inspection
- Multiple Inspection Process Support (SMT & THT)
- Full-Board Imaging for High Speed Inspection
- Simultaneous Double-Sided Scanning
- M2M Integration Capabilities with PnP Machine
- Offline Debugging
- Feedback from AOI to Surface Mount Machine



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**AUTO OPTICAL INSPECTION
FRONTIER
SAKI - JAPAN**

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Infrastructure - X Ray

- A high-resolution design can obtain the best image in a very short time for components like BGA, FBGA, QFN, LGA
- Infrared automatic navigation and positioning, quickly select the shooting location
- CNC detection mode, fast automatic detection for multi-point array
- Oblique multi-angle inspection makes it easier to detect sample defects
- The X-ray tube and FDP can be rotated at the same time (0-60°), making the detection image more clear and intuitive



2.5D X-RAY MACHINE

X6600

SEAMARK - CHINA

Infrastructure - PCB Cleaning

- Contain High Efficiency Blowers
- Hybrid Power Option
- Quick Disconnect Spray Bars
- Chemistry Isolation
- Touch Screen Control System
- Consta-Temp VFD system

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**PCB CLEANING MACHINE
POLYSMT 318, NU CLEAN
USA**

Infrastructure - **WAVE**

- Spray Fluxer with Air Knife
- 2 Pre-heating Zones
- Dual Jet Wave
- Dedicated Solder Baths for Lead-Free and Leaded Assembly

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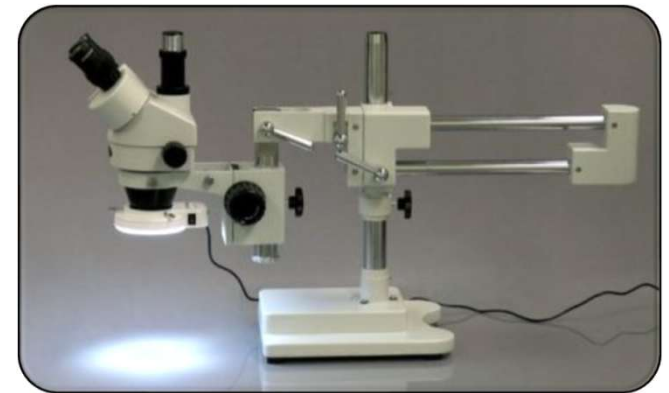


**WAVE SOLDERING MACHINE
STALLION 321FC JW, EMST
INDIA**

Infrastructure - **SCOPE**

- 3.5X-90X Large Zoom Power Microscope on Boom with 54-LED Ring Light
- 45 degree Inclined Trinocular Head
- SUPER Widefield High-Eyepoint Eyepieces
- Adjustable Interpupillary Distance

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**MICROSCOPE
MU500, AMSCOPE
USA**

Infrastructure - **INSERTION** Line

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- Insert 15-20 types of components @ a time
- PCB size: 50mmX50mm to 250mmX600mm
- ESD Safe assembly Line



MANUAL INSERTION LINE
DELHI, INDIA

Certification & Compliances

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In Process for following Certification



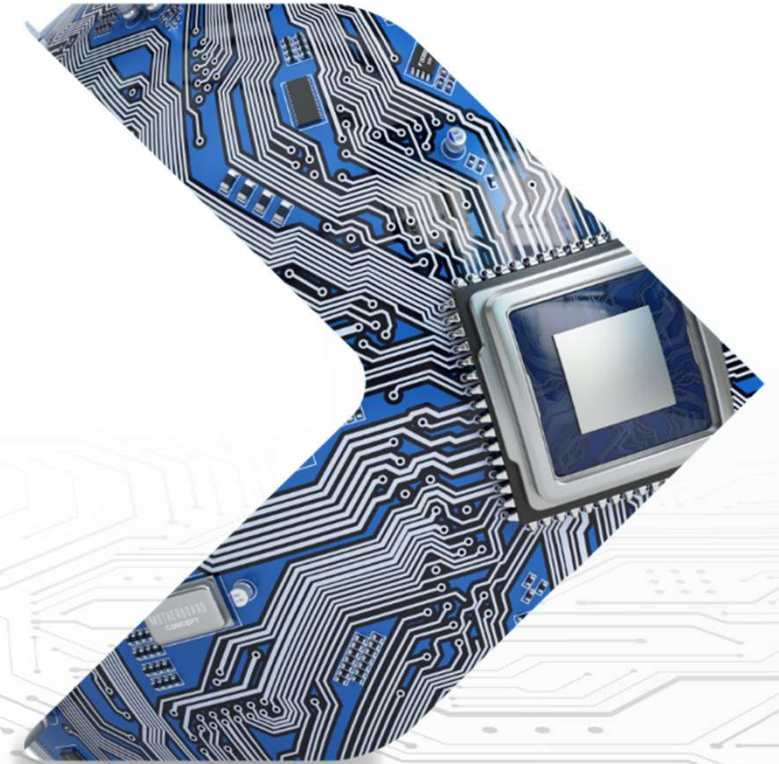
SMT Capabilities

- Screen Printing with 3D Paste Inspection
- State of the Art, High-Speed placement capabilities
- Separate Processes for RoHS / REACH and Leaded Assembly
- Placement of BGA, μ BGA, QFN, 01005 & 0201
- RoHS Complied Reflow Ovens, Multi-Zones Reflow
- Machine Placement Capacity = 120K Chips/Hour
- Placement Accuracy = 30 Microns



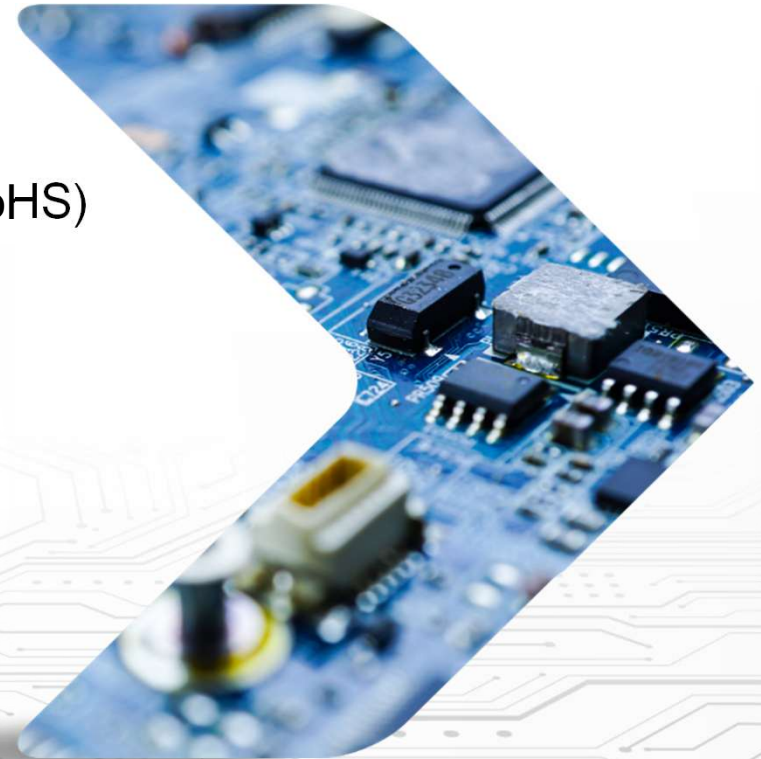
BGA Capabilities

- 30 Micron Placement Accuracy
- Expert BGA Reballing
- Micro-BGA (High pin count)
- BGA Level Measurement via X-Ray
- Any size/package BGA



THT Capabilities

- Advanced Technology Wave Solder (RoHS, Non-RoHS)
- Skilled Manual Soldering
- Leadless / Lead-free Soldering
- Manual Insertion Line



TESTING Capabilities

- Full Product Testing
- Functional Testing
- In-Circuit Testing (ICT)*
- Flying Probe Testing*
- Customized Testing

** outsourced on demand*



NPI (3-7 Days)

Product Application & Design Documents



Box-Build (3-5 Days)

Production Data - BoM, Gerber data
Testing Procedure, 3D data of box fixture



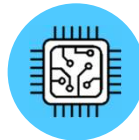
Turnkey (1-3 Days)

Production Data - BoM, Gerber data



Proto / Job-work (1-2 Days)

Production Data - BoM, Gerber data



QUOTE





DfX Analysis

DFM/DFMA to Optimize:

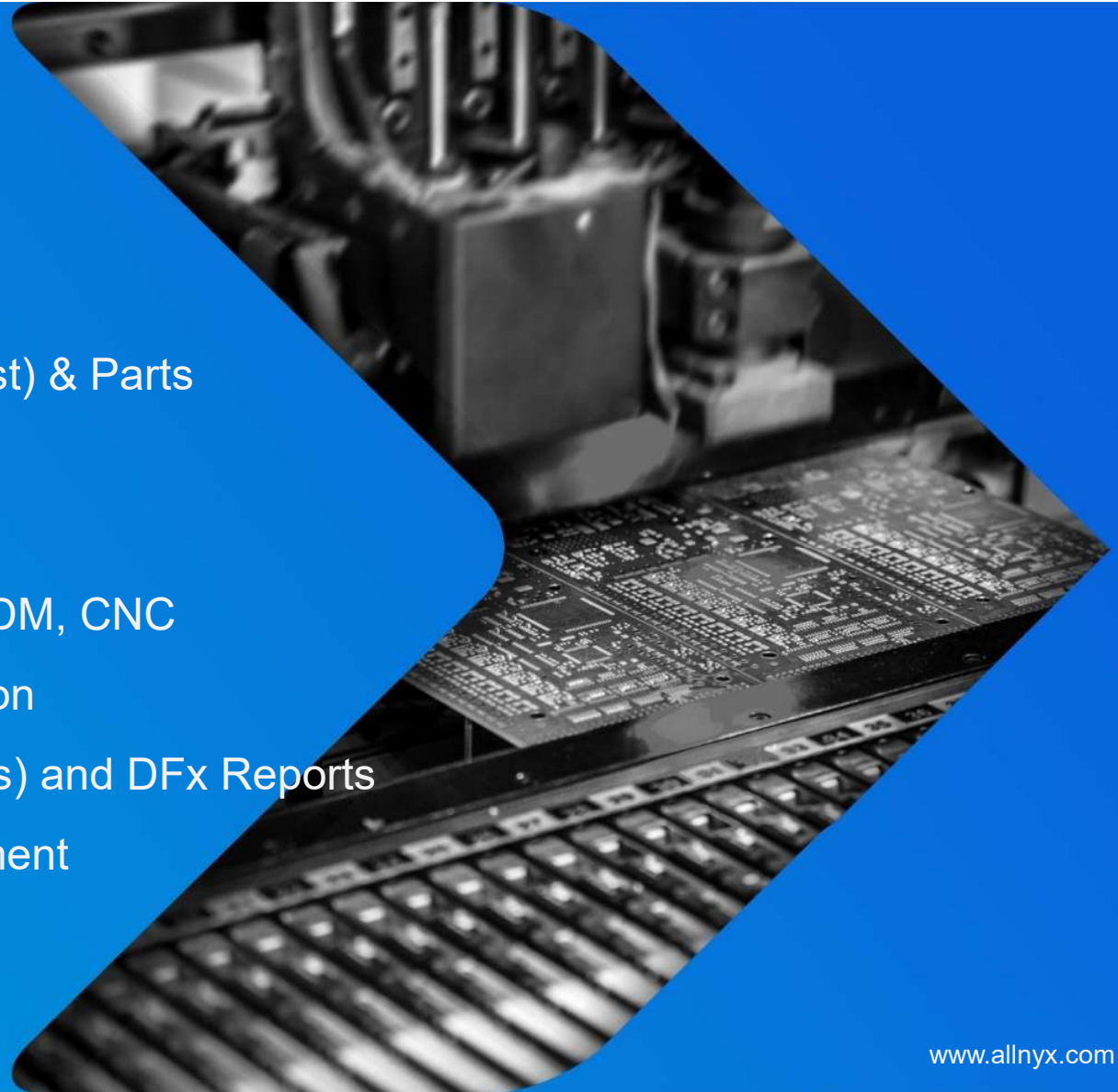
- Product & Design Reliability
- Mechanical Part consolidation
- Manufacturability as per IPC
- BOM Cost and Availability
- EoL/Obsolescence Planning

RAPID Prototype

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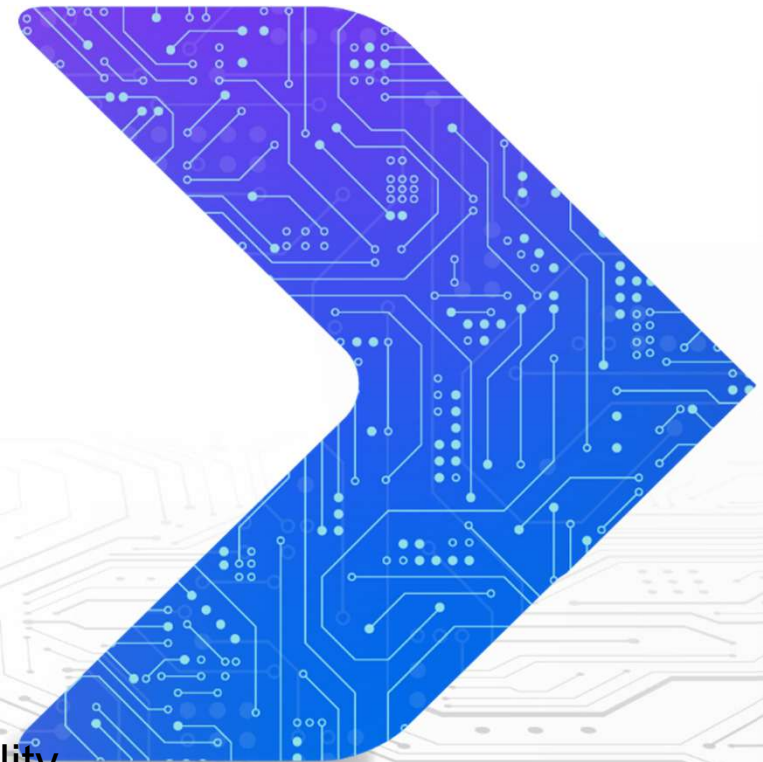
➤ **RAPID** Prototype

- Quick Turn PCB Fabrication
- Component Kit Sourcing
- Strategic AVL (Approved Vendor List) & Parts Management
- Quick Turn PCB Assembly
- Plastic Parts Proto by SLS, SLA, FDM, CNC
- 3D Printing & Metal Parts Fabrication
- FMEA (Failure Mode Effect Analysis) and DFX Reports
- Product Assembly & Test Development
- Analysis and Review Reports for Design Refinement



VALUE Engineering

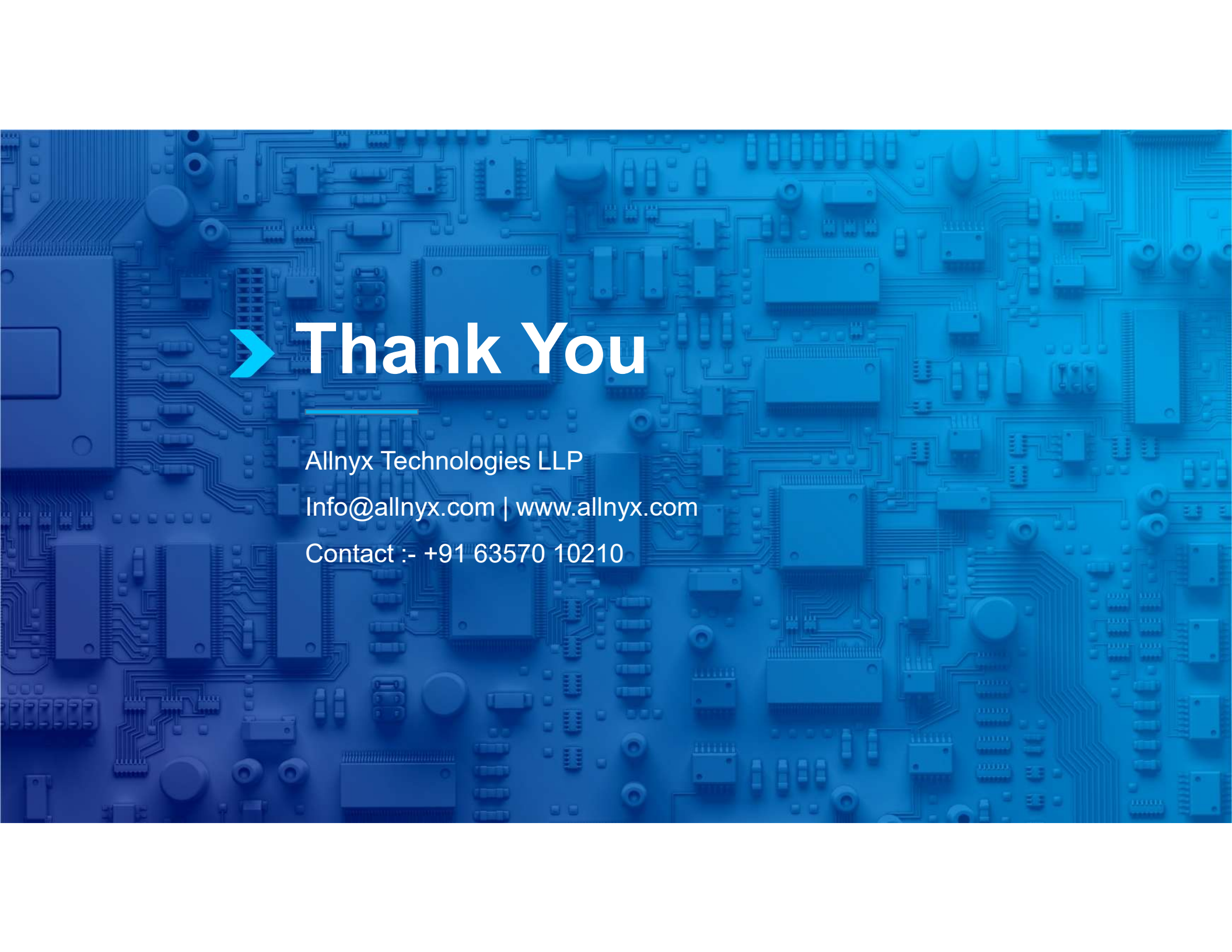
- BoM Analysis & BoM Cost Reduction
- Cost Optimization through Alternate Vendor,
- Component / Material Selection and Sourcing
- Metal Enclosure to Plastic Conversion
- Through Hole to SMT PCB Conversion
- Alternate Design / Design Modifications
- Component Obsolescence Resolution
- Complete Product Revamping
- Enhance Product Features, Performance & Quality



SUPPLY CHAIN Management



- Production, Raw Materials Planning, Forecasting & Ordering
- Delivery Acknowledgment, Planning and Traceability
- Lead Time Reduction through Vendor Process Analysis
- Vendor Development & Vendor Managed Inventory
- Quality Improvement through Process Refinement
- Cost Reduction through Negotiation, Alternate Part and Shipment Consolidation
- Supply Chain Risk Analysis
- Small Batch Procurement and Production for Prototypes and Pilot Run



➤ Thank You

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